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Solidigm Introduces World's First Cold-Plate-Cooled eSSD for Next-Generation Fanless Server Designs

Redefining Cool Storage Solutions for the AI Era

Rancho Cordova, Calif., September 23, 2025 – Solidigm, a pioneer in enterprise data storage, today introduced the only Cold-Plate-Cooled enterprise SSD (eSSD) for fanless server environments.

The industry's first eSSD with single-sided direct-to-chip liquid cooling technology, the Solidigm™ D7-PS1010 E1.S SSD is one of the fastest PCIe 5.0 SSD on the planet for Direct Attach Storage (DAS) AI workloads.[1]

"Solidigm's Cold-Plate-Cooled eSSD is a breakthrough for thermal optimization, unlocking tremendous value inside the most advanced GPU servers," said Greg Matson, Senior Vice President and Head of Products and Marketing, Solidigm. "This is the world's first single-sided Cold-Plate solution that cools both sides of the SSD, delivering the most efficient storage subsystem available to alleviate the strain placed on SSDs in dense AI environments."

Solidigm is working closely with leading server ODMs and OEMs to qualify the Solidigm D7-PS1010 9.5mm and 15mm E1.S SSDs on recommended vendor lists, in addition to other AI and server solutions.

"Supermicro is excited to collaborate with Solidigm on their E1.S form factor Cold-Plate-Cooled eSSD technology," said Vik Malyala, MD Europe, Senior Vice President, Technology and AI, Supermicro. "Their innovative SSDs can be utilized on some of the most advanced liquid-cooled architectures, including the Supermicro NVIDIA HGX B300-based GPU servers supporting compute-intensive workloads."

By delivering targeted cooling directly to critical components on both sides of the SSD, the uniquely innovative thermal solution design helps enable seamless serviceability and improved performance in both liquid and air-cooled environments.

Solidigm's direct-to-chip liquid-cooled eSSD enables data center and edge operators to realize impactful space savings—opening the door for unprecedented GPU scale and density. By minimizing cooling infrastructure requirements, this technology helps to maximize compute deployments even in locations with limited physical footprint.

Designed for leading and next-generation AI server architectures, the Solidigm D7-PS1010 Cold-Plate-Cooled eSSD:

- Addresses the challenges of server thermal management and power efficiency with hot swappable, single-sided cold-plate cooling technology;
- Enables the full operationalization of intensive AI workloads, mitigating any thermal impact to the storage device;
- Delivers high performance and saturates Gen5 bandwidths to help meet AI workload demands; and
- Reduces operational cost, eliminating fans, maximizing thermal efficiency, and enabling smaller server designs.

Solidigm E1.S 9.5mm and 15mm form factors are available in 3.84TB and 7.68TB capacities.

About Solidigm
Solidigm, a pioneer in enterprise data storage, leverages decades of product leadership and technical innovation, collaborating with customers to transform their business and propel them into the data-centric future. Our legacy of industry leadership is helping enable AI and more with our robust end-to-end product portfolio for core data centers to the edge. Headquartered in Rancho Cordova, California, Solidigm operates globally as a standalone subsidiary of SK hynix Inc. Discover how we're advancing the industry at solidigm.com.

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Footnote

[1] The Solidigm D7-PS1010 E1.S has best-in-class 4-corners storage performance specifications versus in-market PCIe 5.0-based E1.S SSDs as of August 2025. For details, reference supporting PCIe 5.0 E1.S performance specifications as published by leading manufacturers.